

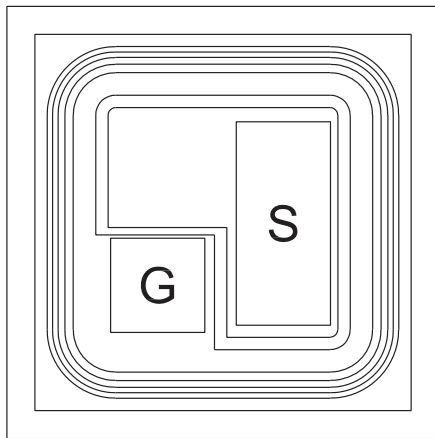
**PROCESS CP354X**  
**Small Signal MOSFET Transistor**  
**N-Channel Enhancement-Mode Transistor Chip**



**PROCESS DETAILS**

Process	EPITAXIAL PLANAR
Die Size	21.7 x 21.7 MILS
Die Thickness	5.5 MILS
Gate Bonding Pad Area	4.7 x 4.7 MILS
Source Bonding Pad Area	4.7 x 10.2 MILS
Top Side Metalization	Al-Si - 37,000Å
Back Side Metalization	Au - 12,000Å

**GEOMETRY**



BACKSIDE DRAIN

R1

**GROSS DIE PER 6 INCH WAFER**

51,400

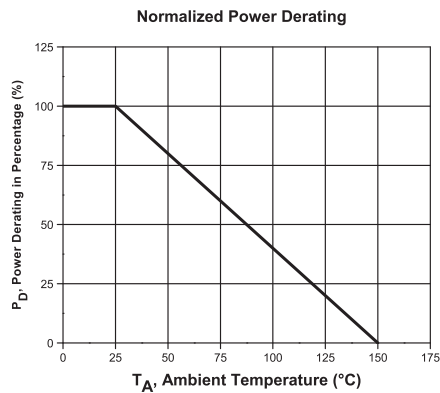
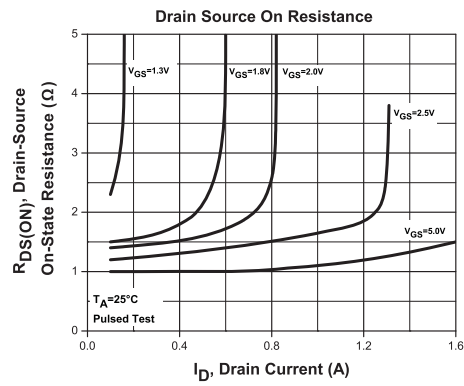
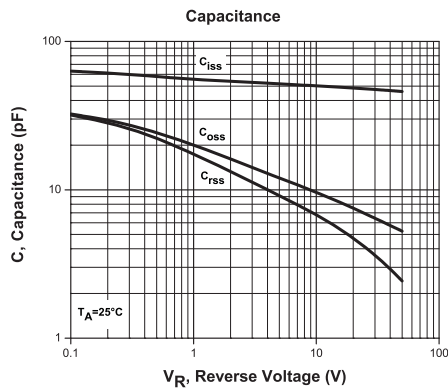
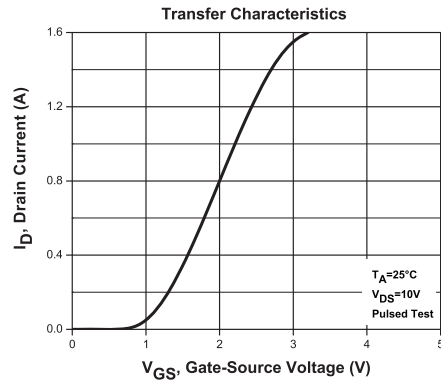
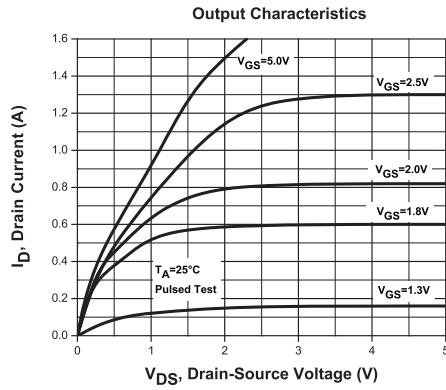
**PRINCIPAL DEVICE TYPES**

CMLM0305  
CMLDM7003  
CMPDM7003  
CTLDM7003-M621

R2 (22-March 2010)

# PROCESS CP354X

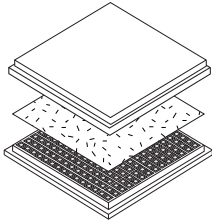
## Typical Electrical Characteristics



R2 (22-March 2010)

## BARE DIE PACKING OPTIONS

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### BARE DIE IN TRAY (WAFFLE) PACK

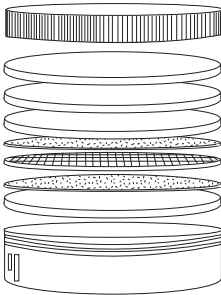
**CT:** Singulated die in tray (waffle) pack.

(example: CP211-PART NUMBER-CT)

**CM:** Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).

(example: CP211-PART NUMBER-CM)

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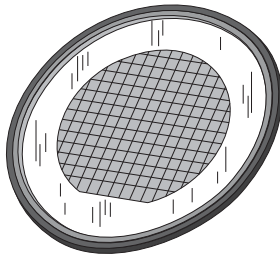


### UNSAWN WAFER

**WN:** Full wafer, unsawn, 100% tested with reject die inked.

(example: CP211-PART NUMBER-WN)

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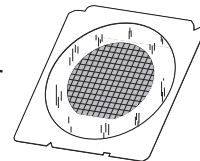


### SAWN WAFER ON PLASTIC RING

**WR:** Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked.

(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



R1 (10-February 2017)

## OUTSTANDING SUPPORT AND SUPERIOR SERVICES



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### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

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### DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

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### CONTACT US

#### Corporate Headquarters & Customer Support Team

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